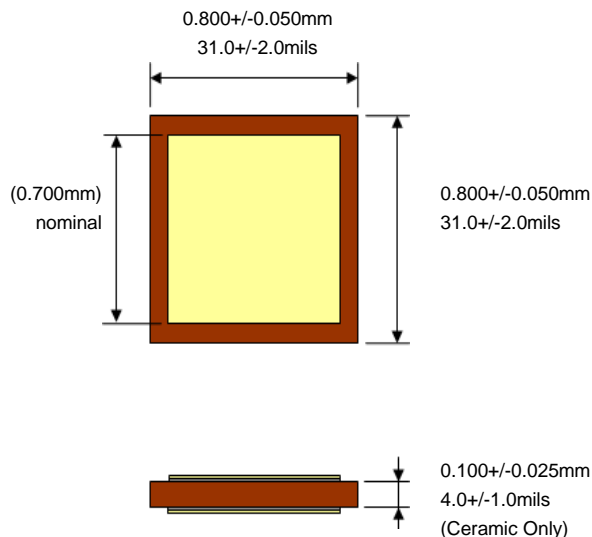




TECDIA CO., LTD.  
 2F Tamachi Kiyota Bldg.  
 4-3-4 Shibaura Minato-ku, Tokyo 108-0023 Japan  
 TEL: 81-3-5765-5400 FAX: 81-3-5765-5404

SPECIFICATION SHEET



Manufactured to metric dimensions. Imperial units are for reference only.

Part Number:	BMS151K2P
Dielectric Constant(K):	2800
Capacitance Value:	150[pF] @ 1kHz, 1 Vrms, 25°C, No DC Bias
Capacitance tolerance:	K (tolerance: ± 10% )
Dissipation Factor (DF):	2.5% Max @ 1kHz, 1 Vrms, 25°C, No DC Bias
Rated working voltage (RWV):	50 V
Insulation Resistance (IR):	100,000MΩ Min @ 50Vdc, 25°C
Dielectric Withstanding Voltage (DWV):	No breakdown @ 125Vdc x 2sec, 25°C
Temperature Characteristic of Capacitance:	±15% (X7R @ -55°C to +125°C) @ No DC Bias
Metallization:	
Top:	TiW - Au 2.5µm Min
Bottom:	TiW - Au 2.5µm Min

NOTES:

- Other specifications not listed are available at [www.tecdia.com](http://www.tecdia.com). Specifications may be subject to change without prior notice.
- RoHS compliant.
- Wire bonding location should be 25µm or further from edges of the electrode to avoid electrode peeling.
- Capacitance, Temperature Coefficient and Dissipation Factor are measured before any AC or DC bias has been applied.
- Recommended Storage Conditions (Waffle Packaging): 23 +/- 10°C @ 60% RH Max
- Guaranteed Shelf Life: 1 year after delivery under recommended storage conditions.
- Epoxy attachment is recommended. Successful wire bonding and die attachment are dependent on the types of bonding tools and conditions used. Please check the wire bonding and die attach conditions of your site to prevent the wire/electrode from peeling or detaching. Tecdia is not responsible for mechanical issues such as cracking or detaching that can occur when solder die mounting.

PREPARED BY: M. Simpson <u>2020/1/14</u>	DESCRIPTION: CHIP CAPACITOR	Scale: Not to Scale
APPROVED BY: T. Yoshikawa <u>2020/1/14</u>	TECDIA PART NUMBER: BMS151K2P	SHEET: 1 of 1